Titles of Most Frequently Occurring Classifications of Patents Returne d

From A Search of 09548826 on February 20, 2004

7 714/718 (4 OR, 3 XR)

Class 714: ERROR DETECTION/CORRECTION AND FAULT

DETECTION/RECOVERY

714/699 PULSE OR DATA ERROR HANDLING

714/718 .Memory testing

6 324/755 (1 OR, 5 XR)

Class 324: ELECTRICITY: MEASURING AND TESTING

324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF ELECTRIC COMPONENTS

324/537 .Of individual circuit component or element

324/754 ..With probe elements

324/755 ...Internal of or on support for device under

test (DUT)

6 324/765 (3 OR, 3 XR)

Class 324: ELECTRICITY: MEASURING AND TESTING

324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF

ELECTRIC COMPONENTS

324/537 .Of individual circuit component or element

324/765 .. Test of semiconductor device

6 365/201 (4 OR, 2 XR)

Class 365: STATIC INFORMATION STORAGE AND RETRIEVAL

365/189.01 READ/WRITE CIRCUIT

365/201 .Testing

4 257/203 (1 OR, 3 XR)

Class 257: ACTIVE SOLID-STATE DEVICES

257/202 GATE ARRAYS

257/203 .With particular chip input/output means

4 257/48 (3 OR, 1 XR)

Class 257: ACTIVE SOLID-STATE DEVICES 257/48 TEST OR CALIBRATION STRUCTURE

4 257/723 (0 OR, 4 XR)

Class 257: ACTIVE SOLID-STATE DEVICES

257/688 .With large area flexible electrodes in press

contact with opposite sides of active semi

conductor chip

and surrounded by an insulating element, e

.g., ring

257/723 .For plural devices

4 365/233 (0 OR, 4 XR)

Class 365: STATIC INFORMATION STORAGE AND RETRIEVAL

365/230.01 ADDRESSING

365/233 .Sync/clocking

3 257/E21.525 (0 OR, 3 XR)

Class 257: ACTIVE SOLID-STATE DEVICES

257/E21.515 .....Involving use of mechanical auxiliary par

t

without use of alloying or soldering pro

cess, e.g.,

pressure contacts (EPO)

257/E21.521 .Testing or measuring during manufacture or treatment or reliability measurement, i.e.

, testing of

parts followed by no processing which modi

fies parts as

such (EPO)

257/E21.525 ..Procedures, i.e., sequence of activities consisting of plurality of measurement and correction,

marking or sorting steps (EPO)

3 257/E23.171 (0 OR, 3 XR)

Class 257: ACTIVE SOLID-STATE DEVICES

257/E23.139 ...Liquid at normal operating temperature of device (EPO)

257/E23.141 .Arrangements for conducting electric current within device in operation from one compo

nent to another,

interconnections, e.g., wires, lead frame

s (EPO)

257/E23.169 ..Interconnection structure between plurality of semiconductor chips being formed on or

in insulating

substrates (EPO)

257/E23.171 ...Adaptable interconnections, e.g., for engineering changes (EPO)

3 257/E25.023 (0 OR, 3 XR)

Class 257: ACTIVE SOLID-STATE DEVICES

257/E25.001 ASSEMBLIES CONSISTING OF PLURALITY OF

INDIVIDUAL SEMICONDUCTOR OR OTHER SOLID-

STATE DEVICES (EPO)

				09548826 CLSTITLES
	257/E25.002		/E25.002	
		257	/E25.022	
		257	/E25.023	
or	· C.C	omponents		compositation of conceptorial beautiful actions
		_	: <b>+</b>	formed in or on common substrate, e.g., int
eg	IIa	ced circu	1.6	device (EPO)
	2	224/150	1 / (	OR, 3 XR)
	3	724/130. Cla	1 (0	: ELECTRICITY: MEASURING AND TESTING
				MISCELLANEOUS
	3	333/247	(3	OR, 0 XR)
	•			: WAVE TRANSMISSION LINES AND NETWORKS
		333	/245	LONG LINE ELEMENTS AND COMPONENTS
				.Strip type
		333	/247	Semiconductor mounts
	3	365/200	(2	OR, 1 XR)
				: STATIC INFORMATION STORAGE AND RETRIEVAL
				READ/WRITE CIRCUIT
		365	/200	.Bad bit
	3	438/15	(2	OR, 1 XR)
		Cla	ss 438	: SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
		438	/14	WITH MEASURING OR TESTING
		438	/15	.Packaging (e.g., with mounting, encapsulating
r				etc.) or treatment of packaged semiconducto
	3	714/724		OR, 2 XR)
		CIa	ss 714	: ERROR DETECTION/CORRECTION AND FAULT DETECTION/RECOVERY
		714	/699	PULSE OR DATA ERROR HANDLING
			/724	.Digital logic testing
	2	257/678	( (	OR, 2 XR)
	_		•	: ACTIVE SOLID-STATE DEVICES
		257	/678	HOUSING OR PACKAGE
	2	257/730	10	OR, 2 XR)
	_			: ACTIVE SOLID-STATE DEVICES
			/688	.With large area flexible electrodes in press
				contact with opposite sides of active semi

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conductor chip
and surrounded by an insulating element, e
.g., ring
257/730 .Outside periphery of package having specified
shape or configuration
2 257/777 (0 OR, 2 XR)
Class 257: ACTIVE SOLID-STATE DEVICES
257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD
257/777 Cohip mounted on chip
2377777 Chip mounted on chip
0 057/770
2 257/778 (1 OR, 1 XR)
Class 257: ACTIVE SOLID-STATE DEVICES
257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD
257/778 .Flip chip
2 257/E21.512 (0 OR, 2 XR)
Class 257: ACTIVE SOLID-STATE DEVICES
257/E21.001 PROCESSES OR APPARATUS ADAPTED FOR MANUFACTURE
OR TREATMENT OF SEMICONDUCTOR OR SOL
ID-STATE DEVICES
OR OF
PARTS THEREOF (EPO)
257/E21.002 .Manufacture or treatment of semiconductor
device (EPO)
257/E21.04 Device having at least one potential-jump
barrier or surface barrier, e.g., PN j
unction,
depletion
layer, carrier concentration layer (EP

0)

257/E21.499 ... Assembling semiconductor devices, e.g., packaging , including mounting, encapsu

lating, or
treatment

of packaged semiconductor (EPO)
257/E21.506 ....Attaching or detaching leads or other
conductive members, to be used for carry

ing current to or

from device in operation (EPO)
257/E21.509 ....Involving soldering or alloying process,
e.g., soldering wires (EPO)

257/E21.511 .....Mounting on insulating member provided with metallic leads, e.g., flip-chip mount

ing, conductive

die mounting (EPO)

	257/E21.512	09548826_CLSTITLESRight-up bonding (EPO)
2 257/		OR, 2 XR) : ACTIVE SOLID-STATE DEVICES PACKAGING, INTERCONNECTS, AND MARKINGS FOR SEMICONDUCTOR OR OTHER SOLID-STATE DEVICE
S (EPO)	257/E23.003 257/E23.004	<pre>.Mountings, e.g., nondetachable insulating     substrates (EPO)Characterized by shape (EPO)</pre>
	257/E23.001	OR, 2 XR) : ACTIVE SOLID-STATE DEVICES PACKAGING, INTERCONNECTS, AND MARKINGS FOR SEMICONDUCTOR OR OTHER SOLID-STATE DEV
ICES (EPO	) 257/E23.01	.Arrangements for conducting electric current to or from solid-state body in operatio
n, e.g.,	leads,	· · · · · · · · · · · · · · · · · · ·
	257/E23.023	terminal arrangements (EPO)Consisting of soldered or bonded constructions (EPO)
	257/E23.06	Leads, i.e., metallizations or lead frames
iers (EPO	)	on insulating substrates, e.g., chip carr
TCIB (BIO	257/E23.068	Additional leads joined to metallizations on insulating substrate, e.g., pins, bumps
, wires,	flat	
	257/E23.069	<pre>leads (EPO)Spherical bumps on substrate for external connection, e.g., ball grid arrays (BGA) (E</pre>
PO)		
2 257/		OR, 2 XR) : ACTIVE SOLID-STATE DEVICES PACKAGING, INTERCONNECTS, AND MARKINGS FOR SEMICONDUCTOR OR OTHER SOLID-STATE DEVI
CES (EPO)		DESTRUCTION ON OTHER BUILD BINTED BUY
	257/E23.01	.Arrangements for conducting electric current to or from solid-state body in operation
, e.g., l	eads,	towning 1 common to (FDC)
	057/500 000	terminal arrangements (EPO)Consisting of soldered or bonded
	257/E23.023	
ers (EPO)	257/E23.023 257/E23.06	<pre>constructions (EPO)Leads, i.e., metallizations or lead frames   on insulating substrates, e.g., chip carri</pre>

2	324/500 324/537	324	: ELECTRICITY: MEASURING AND TESTING FAULT DETECTING IN ELECTRIC CIRCUITS AND OF ELECTRIC COMPONENTS .Of individual circuit component or element
2	324/754 324/758 Class 324/500 324/537 324/754	(0 324	: ELECTRICITY: MEASURING AND TESTING
2	324/758 333/33	(0 333	<ul><li>Probe alignment or positioning</li><li>OR, 2 XR)</li><li>: WAVE TRANSMISSION LINES AND NETWORKS</li></ul>
	333/32 333/33		.With impedance matchingHaving long line elements
2	•		OR, 2 XR) : ELECTRICITY: ELECTRICAL SYSTEMS AND DEVICES
	361/600 361/679 361/683 361/684		HOUSING OR MOUNTING ASSEMBLIES WITH DIVERSE ELECTRICAL COMPONENTS .For electronic systems and devicesComputer related supportMemory unit support
2	361/783 Class		OR, 2 XR) : ELECTRICITY: ELECTRICAL SYSTEMS AND DEVICES
	361/600 361/679 361/748 361/760 361/783		HOUSING OR MOUNTING ASSEMBLIES WITH DIVERSE ELECTRICAL COMPONENTS .For electronic systems and devicesPrinted circuit boardConnection of components to boardHaving semiconductive device
2	365/230	365 .01	OR, 2 XR) : STATIC INFORMATION STORAGE AND RETRIEVAL ADDRESSING .Plural blocks or banks
2	713/2 Class		OR, 0 XR) : ELECTRICAL COMPUTERS AND DIGITAL PROCESSING

UP,	713/1		09548826_CLSTITLES SYSTEMS: SUPPORT DIGITAL DATA PROCESSING SYSTEM INITIALIZATION OR CONFIGURATION (E.G., INITIALIZING, SET
	713/2		CONFIGURATION, OR RESETTING) .Loading initialization program (e.g., booting
, 00	1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.		rebooting, warm booting, remote booting, BI
05,	initial		<pre>program load (IPL), bootstrapping)</pre>
2	714/25 Class		: ERROR DETECTION/CORRECTION AND FAULT
	714/100		DETECTION/RECOVERY DATA PROCESSING SYSTEM ERROR OR FAULT HANDLING
	714/1 714/25		<pre>.Reliability and availabilityFault locating (i.e., diagnosis or testing)</pre>
2	714/44 Class		OR, 1 XR) : ERROR DETECTION/CORRECTION AND FAULT DETECTION/RECOVERY
	714/100		DATA PROCESSING SYSTEM ERROR OR FAULT HANDLING
	714/1 714/25		<pre>.Reliability and availabilityFault locating (i.e., diagnosis or testing)</pre>
	714/40 714/44		Component dependent techniquePeripheral device component fault
2	714/46 Class		: ERROR DETECTION/CORRECTION AND FAULT
	714/100		DETECTION/RECOVERY DATA PROCESSING SYSTEM ERROR OR FAULT HANDLING
	714/1 714/25		<pre>.Reliability and availabilityFault locating (i.e., diagnosis or testing)</pre>
g	714/46		Operator interface for diagnosing or testin
2	714/47 Class	(0 714	
	714/100		DETECTION/RECOVERY DATA PROCESSING SYSTEM ERROR OR FAULT HANDLING

	714/1 714/47	Reliability and availabilityPerformance monitoring for fault avoidance
2	714/732	(1 OR, 1 XR)
	Class	714 : ERROR DETECTION/CORRECTION AND FAULT DETECTION/RECOVERY
	714/699	PULSE OR DATA ERROR HANDLING
	714/724	.Digital logic testing
	714/732	
2	714/733	(1 OR, 1 XR)
	Class	714: ERROR DETECTION/CORRECTION AND FAULT DETECTION/RECOVERY
	714/699	PULSE OR DATA ERROR HANDLING
	714/724	.Digital logic testing
	714/733	Built-in testing circuit (BILBO)

#### 09548826 LIST

PLUS Search Results for S/N 09548826, Searched February 20, 2004

The Patent Linguistics Utility System (PLUS) is a USPTO automated sear ch

system for U.S. Patents from 1971 to the present. PLUS is a query-by-example search system which produces a list of patents that a re

most closely related linguistically to the application searched. This search was prepared by the staff of the Scientific and Technical Information Center, SIRA.

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## 09548826\_LIST

4841434
5805606
5249450
5336649
5342807
5359547
5652754
5727000
5808919
5954827
6049896
6133745
6415397

#### 09548826 CLS

Most Frequently Occurring Classifications of Patents Returned From A Search of 09548826 on February 20, 2004

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4 365/201
   714/718
 3 257/48
 3 324/765
 3 333/247
 2 365/200
 2 438/15
 2 713/2
Cross-Reference Classifications
 5 324/755
 4 257/723
 4 365/233
 3 257/203
 3 257/E21.525
 3 257/E23.171
 3 257/E25.023
 3 324/158.1
 3 324/765
 3 714/718
 2 257/678
 2 257/730
 2 257/777
 2 257/E21.512
 2 257/E23.004
 2 257/E23.069
 2 257/E23.07
 2 324/754
 2 324/758
 2 333/33
 2 361/684
 2 361/783
 2 365/201
 2 365/230.03
 2 714/25
 2 714/47
   714/724
Combined Classifications
 7 714/718
 6
   324/755
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6

324/765 6 365/201

Original Classifications

### 09548826\_CLS

- 257/203 4
- 4 257/48
- 4 257/723
- 4 365/233
- 257/E21.525
- 3 257/E23.171
- 3 257/E25.023
- 3 324/158.1
- 3 333/247
- 3 365/200
- 3 438/15
- 3 714/724
- 2 257/678
- 2 257/730
- 2 257/777
- 2 257/778
- 2 257/E21.512
- 2 257/E23.004
- 257/E23.069
- 2 257/E23.07
- 2 324/754
- 2 324/758
- 2 333/33
- 2 361/684
- 2 361/783
- 2 365/230.03
- 713/2
- 2 2 2 714/25
- 714/44
- 2 714/46
- 2 714/47
- 2 714/732
- 714/733